

TYPE:J1



FOUP Load Port TAS300 TYPE: J1

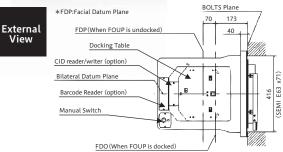


Features

1 SEMI Standard

E15.1-0305 E57-0600 E62-0306 E63-1104 E64-1105 E110-1102 S2-0706 S8-0308 S14-0704

- With all moving parts, including mapping unit, are installed below the wafer surface, which provides high-level particle-free design. The highest level of airflow analysis delivers particle-free design.
- The air-cushioned pneumatic drive on docking plate and FIMS door opening provide calibration-free operation, with a wide variety of FOUPs (Supports 300 mm FOUPs compliant with SEMI E47.1 and E62.)
- 4 Transmission-type mapping unit optionally available.
- 5 High-reliability design delivers trouble-free operation over a long period of time.
- 6 Obstacle detection sensors on Dock position.
- 7 FOUP/Placement detection.
- 8 Easy positioning mechanism to reduce installation time for mounting and dismounting.



	FDO (When FOUP is docked)	\$11/11/1
	Upper Cover 472 Indicators BOLTS Plane 493	(90)
166,5	FIMS Door Mapping Arm (option) Horizontal Datum Plane	276)
1386	Lower Cover Communications Connectors (under cover) Power Connector (under cover) Optical I/O (option) Tube Connector (under cover) (CDA, VAC, EXH)	1189(SEMI EG3 271, 276)
		*unit:mm

Supported FOUPs					
Manufacturer	Type				
Entegris	F300 Auto Pod ; A300-G3 ; SPECTRA				
Shin-Etsu Polymer	FOUP 300E; FOUP 300EX				
Miraial	KT-3003				
Dainichi Shoji	SF300-02				
Others	300-mm FOUPs compliant with SEMI E47.1 and E62				

Standard Specifications				
External Dimensions and Weight	Full H	leight	1,386mm	
	Full Width		472mm	
	Depth		493mm (from BOLTS plane)	
	Weight		30kg(excluding options)	
Operation Times	Without	Load	Max. 8sec(FOUP set	→ Robot access enable)
	mapping	Unload	Max. 8sec(Robot access enable → FOUP eject enable)	
	With	Load	Max.11sec(FOUP set → Robot access enable)	
	mapping	Unload	Max. 8sec(Robot access enable → FOUP eject enable)	
	FOUP	clamp	Front retaining featur	e (Air driven)
	FOUP door lock		Vacuum suction	
Docking	Docking stroke		70mm	
Mechanism	Repetition accuracy		±0.1mm	
	Distance from FDP to FIMS door		165.0mm	
	Distance from FDP to frame		167.0mm	
	Clean dry air	Pressure	0.52-0.60MPa (G)	6-mm outer-diameter air tube
		Flow	30L/min (ANR)	
	Vacuum	Pressure	-61 ± 10kPa (G)	6-mm outer-diameter air tube
Utilities		Flow	10L/min (ANR)	
	Exha	ust		6-mm outer-diameter air tube
	Noi	se	MAX 60dB (Aeq)	
	Power Source		24 VDC ± 5%, 3A(2-A a	t full load) Breaking capacity:50A
Interface	Communication		RS232C	

Options				
Power Cable	Length	2m; 4 m; 6 m		
	Keyence	BL-601; SR-610		
Carrier ID	Omron	V640		
Reader/	Brooks	LF80 ; LF60 Eco ; LF60 Solid		
Writer	Crossing Automation	ATR9100; PB-90		
	Details ab	out other CIDs available on request.		
E84	Optical I/O only	Hokuyo Automatic DMS-HB1; DMG-HB1		
	Serial comm. control	Details available on request.		
Interface		Ethernet (Details available on request.)		
Comm. Protocol		SECS (Details available on request.)		
Info Pad	Info pads A, B	Electrical detection and lockout pins		
Pin	Info pads C, D	Lockout pins		
Doubled-wafer detection sensor		Detects presence of two wafers in single slot. Details available on request.		
Protrusion detection sensor for quart-glass wafers		Detection characteristics vary for each FOUP. Details available on request.		

Safety and Usage Precautions TDK has prepared documentation providing important safety precautions and explaining how to use this equipment correctly and efficiently. Please request this documentation and read through it before using this equipment.

